



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Sectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-03-08
Company Unique ID	NL 008751171801		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacobello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPS0560Z	HJUF*NHBY106	A	Z55A	2018-03-08
Amount	UoM	Unit type	ST ECOPACK Grade	
9	mg	Each	ECOPACK® 2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Alloy 42		

Package Designator	Size	Nbr of instances	Shape	
DSO	2.672X1.57X1.094	2	gull wing	
Comment	Package: SOD 123 2L 1.0mm			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 15th December 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	1.04	Die - Leadframe	115444

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	HJUF*NHBY106				5000000.0	1000000.0				
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	M-011 Other inorganic materials	0.585	mg	supplier	die	Silicon (Si)	7440-21-3		0.548	mg	936752	60889				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.027	mg	46155	3001				
				supplier	passivation	Nickel (Ni)	7440-02-0		0.003	mg	5128	333				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	1709	111				
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	1709	111				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.004	mg	6838	444				
Leadframe	M-004 Copper and its alloys	2.606	mg	supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	1709	111				
				supplier	alloy	Iron (Fe)	7439-89-6		1.458	mg	559478	162000				
				supplier	alloy	Nickel (Ni)	7440-02-0		1.036	mg	397544	115111				
				supplier	alloy	Manganese (Mn)	7439-96-5		0.015	mg	5757	1667				
				supplier	alloy	Chromium (Cr)	7440-47-3		0.003	mg	1151	333				
				supplier	alloy	Cobalt (Co)	7440-48-4		0.013	mg	4988	1444				
Bonding wires	M-008 Precious metals	0.024	mg	supplier	alloy	Silicon (Si)	7440-21-3		0.004	mg	1535	444				
				supplier	metallization	Silver (Ag)	7440-22-4		0.077	mg	29547	8556				
				supplier	wire	Gold (Au)	7440-57-5		0.024	mg	1000000	2667				
				Encapsulation	M-011 Other inorganic materials	5.604	mg	supplier	mold compound	SiO2	60676-86-0		4.893	mg	873126	543667
								supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		0.280	mg	49964	31111
								supplier	mold compound	Phenol Resin	26834-02-6		0.280	mg	49964	31111
supplier	mold compound	Aromatic poly-phosphate	139189-30-3		0.140	mg	24982	15556								
supplier	mold compound	Carbon Black	1333-86-4		0.011	mg	1964	1222								
connections coating	Solder	0.181	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.181	mg	1000000	20111				